Microchip Technology - DSPIC33EP64MC502-E/SS Datasheet

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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	dsPIC
Core Size	16-Bit
Speed	60 MIPs
Connectivity	CANbus, I²C, IrDA, LINbus, QEI, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, Motor Control PWM, POR, PWM, WDT
Number of I/O	21
Program Memory Size	64KB (22K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	4K x 16
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 6x10b/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	28-SSOP (0.209", 5.30mm Width)
Supplier Device Package	28-SSOP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33ep64mc502-e-ss

TABLE 4-27: PERIPHERAL PIN SELECT OUTPUT REGISTER MAP FOR dsPIC33EPXXXGP/MC204/504 AND PIC24EPXXXGP/MC204 DEVICES ONLY

File Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
RPOR0	0680	—	—	RP35R<5:0>						—	—	RP20R<5:0>						0000
RPOR1	0682	—	—	RP37R<5:0>						—	—	RP36R<5:0>						0000
RPOR2	0684	—	—	RP39R<5:0>						—	—	RP38R<5:0>						0000
RPOR3	0686	—	—	RP41R<5:0>						—	—	RP40R<5:0>						0000
RPOR4	0688	—	—	RP43R<5:0>						—	—	RP42R<5:0>						0000
RPOR5	068A	—	—	RP55R<5:0>						—	—	RP54R<5:0>						0000
RPOR6	068C	—	—	RP57R<5:0>						—	—	RP56R<5:0>						0000

Legend: — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

TABLE 4-28: PERIPHERAL PIN SELECT OUTPUT REGISTER MAP FOR dsPIC33EPXXXGP/MC206/506 AND PIC24EPXXXGP/MC206 DEVICES ONLY

File Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
RPOR0	0680	—	—	RP35R<5:0>						—	—	RP20R<5:0>						0000
RPOR1	0682	—	—	RP37R<5:0>						—	—	RP36R<5:0>						0000
RPOR2	0684	—	—	RP39R<5:0>						—	—	RP38R<5:0>						0000
RPOR3	0686	—	—	RP41R<5:0>						—	—	RP40R<5:0>						0000
RPOR4	0688	—	—	RP43R<5:0>						—	—	RP42R<5:0>						0000
RPOR5	068A	—	—	RP55R<5:0>						—	—	RP54R<5:0>						0000
RPOR6	068C	—	—	RP57R<5:0>						—	—	RP56R<5:0>						0000
RPOR7	068E	—	—	RP97R<5:0>						—	—	—	—	—	—	—	—	0000
RPOR8	0690	—	—	RP118R<5:0>						—	—	—	—	—	—	—	—	0000
RPOR9	0692	—	—	—	—	—	—	—	—	—	—	RP120R<5:0>						0000

Legend: — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

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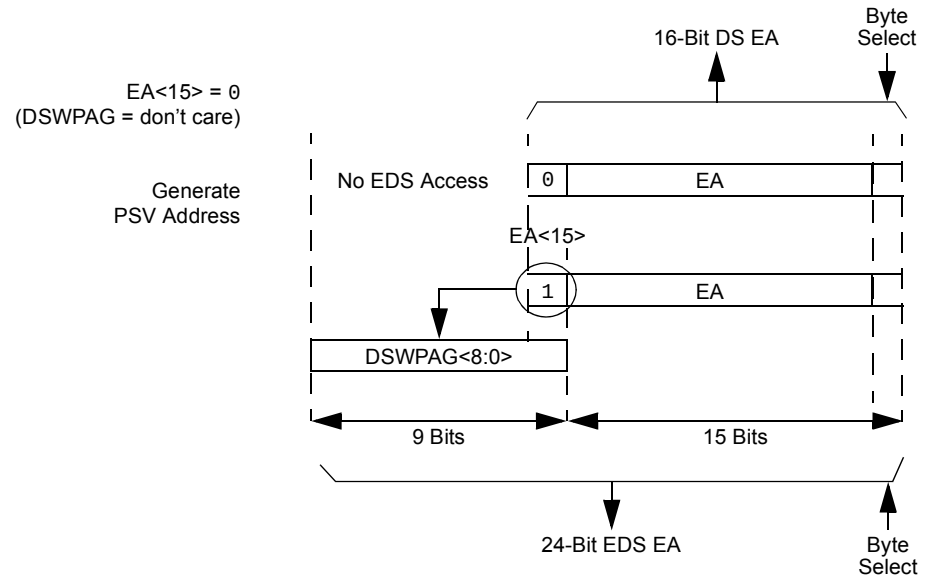
EXAMPLE 4-2: EXTENDED DATA SPACE (EDS) WRITE ADDRESS GENERATION



Note: DS read access when DSRPAG = 0x000 will force an address error trap.

The paged memory scheme provides access to multiple 32-Kbyte windows in the EDS and PSV memory. The Data Space Page registers, DSxPAG, in combination with the upper half of the Data Space address, can provide up to 16 Mbytes of additional address space in the EDS and 8 Mbytes (DSRPAG only) of PSV address space. The paged data memory space is shown in Example 4-3.

The Program Space (PS) can be accessed with a DSRPAG of 0x200 or greater. Only reads from PS are supported using the DSRPAG. Writes to PS are not supported, so DSWPAG is dedicated to DS, including EDS only. The Data Space and EDS can be read from, and written to, using DSRPAG and DSWPAG, respectively.

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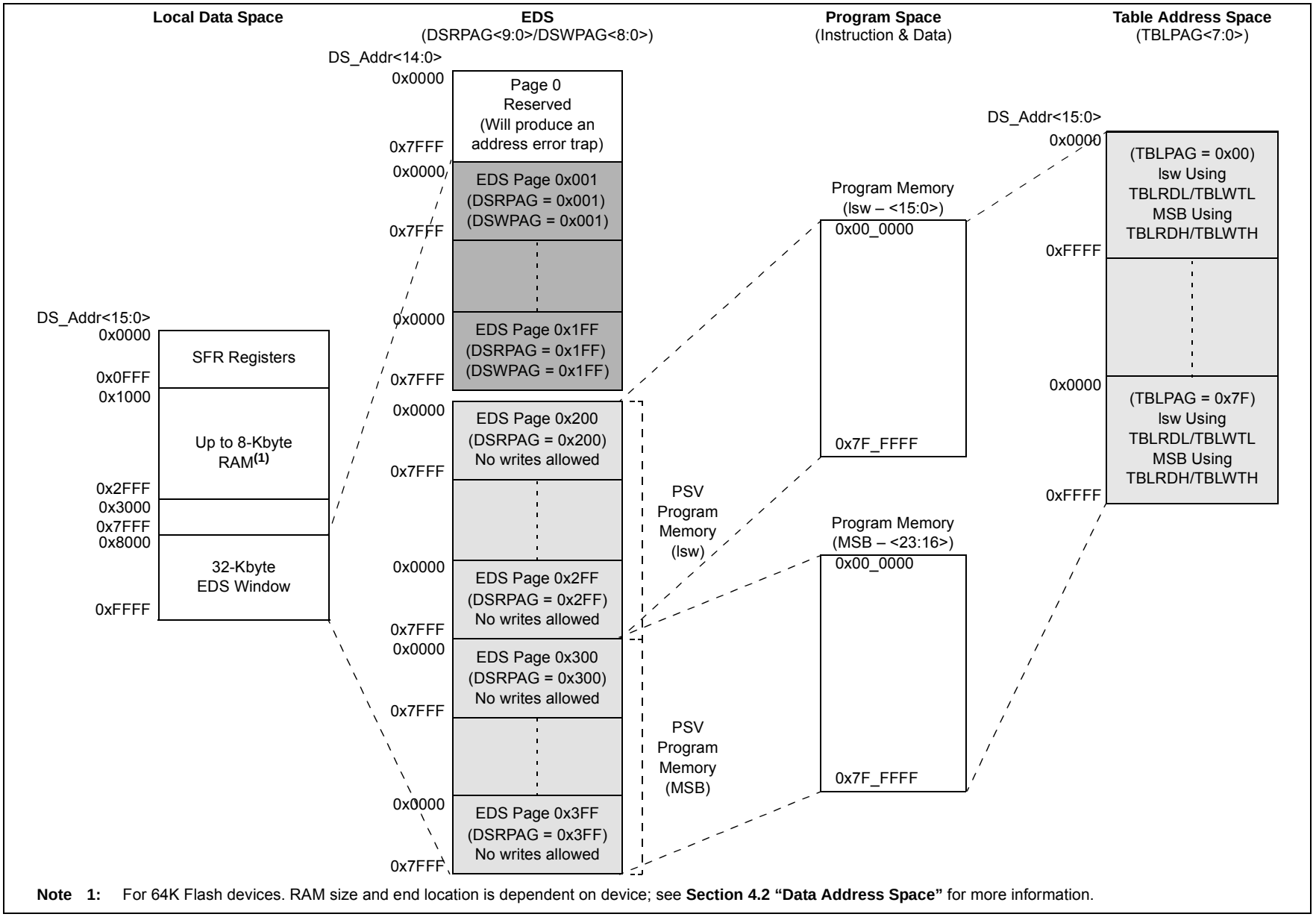
EXAMPLE 4-3: PAGED DATA MEMORY SPACE



Note 1: For 64K Flash devices. RAM size and end location is dependent on device; see **Section 4.2 "Data Address Space"** for more information.

REGISTER 6-1: RCON: RESET CONTROL REGISTER(1) (CONTINUED)

bit 3 **SLEEP:** Wake-up from Sleep Flag bit
1 = Device has been in Sleep mode
0 = Device has not been in Sleep mode

bit 2 **IDLE:** Wake-up from Idle Flag bit
1 = Device was in Idle mode
0 = Device was not in Idle mode

bit 1 **BOR:** Brown-out Reset Flag bit
1 = A Brown-out Reset has occurred
0 = A Brown-out Reset has not occurred

bit 0 **POR:** Power-on Reset Flag bit
1 = A Power-on Reset has occurred
0 = A Power-on Reset has not occurred

Note 1: All of the Reset status bits can be set or cleared in software. Setting one of these bits in software does not cause a device Reset.

2: If the FWDTEN Configuration bit is '1' (unprogrammed), the WDT is always enabled, regardless of the SWDTEN bit setting.

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TABLE 7-1: INTERRUPT VECTOR DETAILS (CONTINUED)

Interrupt Source	Vector #	IRQ #	IVT Address	Interrupt Bit Location		
				Flag	Enable	Priority
QEI1 – QEI1 Position Counter Compare(2)	66	58	0x000088	IFS3<10>	IEC3<10>	IPC14<10:8>
Reserved	67-72	59-64	0x00008A-0x000094	—	—	—
U1E – UART1 Error Interrupt	73	65	0x000096	IFS4<1>	IEC4<1>	IPC16<6:4>
U2E – UART2 Error Interrupt	74	66	0x000098	IFS4<2>	IEC4<2>	IPC16<10:8>
CRC – CRC Generator Interrupt	75	67	0x00009A	IFS4<3>	IEC4<3>	IPC16<14:12>
Reserved	76-77	68-69	0x00009C-0x00009E	—	—	—
C1TX – CAN1 TX Data Request(1)	78	70	0x000A0	IFS4<6>	IEC4<6>	IPC17<10:8>
Reserved	79-84	71-76	0x0000A2-0x0000AC	—	—	—
CTMU – CTMU Interrupt	85	77	0x0000AE	IFS4<13>	IEC4<13>	IPC19<6:4>
Reserved	86-101	78-93	0x0000B0-0x0000CE	—	—	—
PWM1 – PWM Generator 1(2)	102	94	0x0000D0	IFS5<14>	IEC5<14>	IPC23<10:8>
PWM2 – PWM Generator 2(2)	103	95	0x0000D2	IFS5<15>	IEC5<15>	IPC23<14:12>
PWM3 – PWM Generator 3(2)	104	96	0x0000D4	IFS6<0>	IEC6<0>	IPC24<2:0>
Reserved	105-149	97-141	0x0001D6-0x00012E	—	—	—
ICD – ICD Application	150	142	0x000142	IFS8<14>	IEC8<14>	IPC35<10:8>
JTAG – JTAG Programming	151	143	0x000130	IFS8<15>	IEC8<15>	IPC35<14:12>
Reserved	152	144	0x000134	—	—	—
PTGSTEP – PTG Step	153	145	0x000136	IFS9<1>	IEC9<1>	IPC36<6:4>
PTGWDT – PTG Watchdog Time-out	154	146	0x000138	IFS9<2>	IEC9<2>	IPC36<10:8>
PTG0 – PTG Interrupt 0	155	147	0x00013A	IFS9<3>	IEC9<3>	IPC36<14:12>
PTG1 – PTG Interrupt 1	156	148	0x00013C	IFS9<4>	IEC9<4>	IPC37<2:0>
PTG2 – PTG Interrupt 2	157	149	0x00013E	IFS9<5>	IEC9<5>	IPC37<6:4>
PTG3 – PTG Interrupt 3	158	150	0x000140	IFS9<6>	IEC9<6>	IPC37<10:8>
Reserved	159-245	151-245	0x000142-0x0001FE	—	—	—
Lowest Natural Order Priority						

Note 1: This interrupt source is available on dsPIC33EPXXXGP50X and dsPIC33EPXXXMC50X devices only.

2: This interrupt source is available on dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X devices only.

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REGISTER 9-5: REFOCON: REFERENCE OSCILLATOR CONTROL REGISTER

R/W-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
ROON	—	ROSSLP	ROSEL	RODIV3(1)	RODIV2(1)	RODIV1(1)	RODIV0(1)
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **ROON:** Reference Oscillator Output Enable bit
1 = Reference oscillator output is enabled on the REFCLK pin(2)
0 = Reference oscillator output is disabled

bit 14 **Unimplemented:** Read as '0'

bit 13 **ROSSLP:** Reference Oscillator Run in Sleep bit
1 = Reference oscillator output continues to run in Sleep
0 = Reference oscillator output is disabled in Sleep

bit 12 **ROSEL:** Reference Oscillator Source Select bit
1 = Oscillator crystal is used as the reference clock
0 = System clock is used as the reference clock

bit 11-8 **RODIV<3:0>:** Reference Oscillator Divider bits(1)
1111 = Reference clock divided by 32,768
1110 = Reference clock divided by 16,384
1101 = Reference clock divided by 8,192
1100 = Reference clock divided by 4,096
1011 = Reference clock divided by 2,048
1010 = Reference clock divided by 1,024
1001 = Reference clock divided by 512
1000 = Reference clock divided by 256
0111 = Reference clock divided by 128
0110 = Reference clock divided by 64
0101 = Reference clock divided by 32
0100 = Reference clock divided by 16
0011 = Reference clock divided by 8
0010 = Reference clock divided by 4
0001 = Reference clock divided by 2
0000 = Reference clock

bit 7-0 **Unimplemented:** Read as '0'

Note 1: The reference oscillator output must be disabled (ROON = 0) before writing to these bits.
2: This pin is remappable. See **Section 11.4 "Peripheral Pin Select (PPS)"** for more information.

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g) The TRISx registers control *only* the digital I/O output buffer. Any other dedicated or remappable active “output” will automatically override the TRIS setting. The TRISx register *does not* control the digital logic “input” buffer. Remappable digital “inputs” do not automatically override TRIS settings, which means that the TRISx bit must be set to input for pins with only remappable input function(s) assigned

h) All analog pins are enabled by default after any Reset and the corresponding digital input buffer on the pin has been disabled. Only the Analog Pin Select registers control the digital input buffer, *not* the TRISx register. The user must disable the analog function on a pin using the Analog Pin Select registers in order to use any “digital input(s)” on a corresponding pin, no exceptions.

11.6 I/O Ports Resources

Many useful resources are provided on the main product page of the Microchip web site for the devices listed in this data sheet. This product page, which can be accessed using this link, contains the latest updates and additional information.

Note:	In the event you are not able to access the product page using the link above, enter this URL in your browser: http://www.microchip.com/wwwproducts/Devices.aspx?dDocName=en555464

11.6.1 KEY RESOURCES

- **“I/O Ports”** (DS70598) in the *“dsPIC33/PIC24 Family Reference Manual”*
- Code Samples
- Application Notes
- Software Libraries
- Webinars
- All Related *“dsPIC33/PIC24 Family Reference Manual”* Sections
- Development Tools

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REGISTER 15-1: OCxCON1: OUTPUT COMPARE x CONTROL REGISTER 1 (CONTINUED)

bit 3 **TRIGMODE:** Trigger Status Mode Select bit
- 1 = TRIGSTAT (OCxCON2<6>) is cleared when OCxRS = OCxTMR or in software
- 0 = TRIGSTAT is cleared only by software

bit 2-0 **OCM<2:0>:** Output Compare x Mode Select bits
- 111 = Center-Aligned PWM mode: Output set high when OCxTMR = OCxR and set low when OCxTMR = OCxRS(1)
- 110 = Edge-Aligned PWM mode: Output set high when OCxTMR = 0 and set low when OCxTMR = OCxR(1)
- 101 = Double Compare Continuous Pulse mode: Initializes OCx pin low, toggles OCx state continuously on alternate matches of OCxR and OCxRS
- 100 = Double Compare Single-Shot mode: Initializes OCx pin low, toggles OCx state on matches of OCxR and OCxRS for one cycle
- 011 = Single Compare mode: Compare event with OCxR, continuously toggles OCx pin
- 010 = Single Compare Single-Shot mode: Initializes OCx pin high, compare event with OCxR, forces OCx pin low
- 001 = Single Compare Single-Shot mode: Initializes OCx pin low, compare event with OCxR, forces OCx pin high
- 000 = Output compare channel is disabled

Note 1: OCxR and OCxRS are double-buffered in PWM mode only.

2: Each Output Compare x module (OCx) has one PTG clock source. See **Section 24.0 “Peripheral Trigger Generator (PTG) Module”** for more information.
PTGO4 = OC1
PTGO5 = OC2
PTGO6 = OC3
PTGO7 = OC4

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REGISTER 15-2: OCxCON2: OUTPUT COMPARE x CONTROL REGISTER 2

R/W-0	R/W-0	R/W-0	R/W-0	U-0	U-0	U-0	R/W-0
FLTMD	FLTOUT	FLTTRIEN	OCINV	—	—	—	OC32
bit 15							bit 8

R/W-0	R/W-0, HS	R/W-0	R/W-0	R/W-1	R/W-1	R/W-0	R/W-0
OCTRIG	TRIGSTAT	OCTRIS	SYNCSEL4	SYNCSEL3	SYNCSEL2	SYNCSEL1	SYNCSEL0
bit 7							bit 0

Legend:	HS = Hardware Settable bit		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **FLTMD:** Fault Mode Select bit
1 = Fault mode is maintained until the Fault source is removed; the corresponding OCFLTx bit is cleared in software and a new PWM period starts
0 = Fault mode is maintained until the Fault source is removed and a new PWM period starts

bit 14 **FLTOUT:** Fault Out bit
1 = PWM output is driven high on a Fault
0 = PWM output is driven low on a Fault

bit 13 **FLTTRIEN:** Fault Output State Select bit
1 = OCx pin is tri-stated on a Fault condition
0 = OCx pin I/O state is defined by the FLTOUT bit on a Fault condition

bit 12 **OCINV:** Output Compare x Invert bit
1 = OCx output is inverted
0 = OCx output is not inverted

bit 11-9 **Unimplemented:** Read as '0'

bit 8 **OC32:** Cascade Two OCx Modules Enable bit (32-bit operation)
1 = Cascade module operation is enabled
0 = Cascade module operation is disabled

bit 7 **OCTRIG:** Output Compare x Trigger/Sync Select bit
1 = Triggers OCx from the source designated by the SYNCSELx bits
0 = Synchronizes OCx with the source designated by the SYNCSELx bits

bit 6 **TRIGSTAT:** Timer Trigger Status bit
1 = Timer source has been triggered and is running
0 = Timer source has not been triggered and is being held clear

bit 5 **OCTRIS:** Output Compare x Output Pin Direction Select bit
1 = OCx is tri-stated
0 = Output Compare x module drives the OCx pin

Note 1: Do not use the OCx module as its own Synchronization or Trigger source.

2: When the OCy module is turned OFF, it sends a trigger out signal. If the OCx module uses the OCy module as a Trigger source, the OCy module must be unselected as a Trigger source prior to disabling it.

3: Each Output Compare x module (OCx) has one PTG Trigger/Synchronization source. See **Section 24.0 "Peripheral Trigger Generator (PTG) Module"** for more information.
PTGO0 = OC1
PTGO1 = OC2
PTGO2 = OC3
PTGO3 = OC4

REGISTER 17-3: QEI1STAT: QEI1 STATUS REGISTER (CONTINUED)

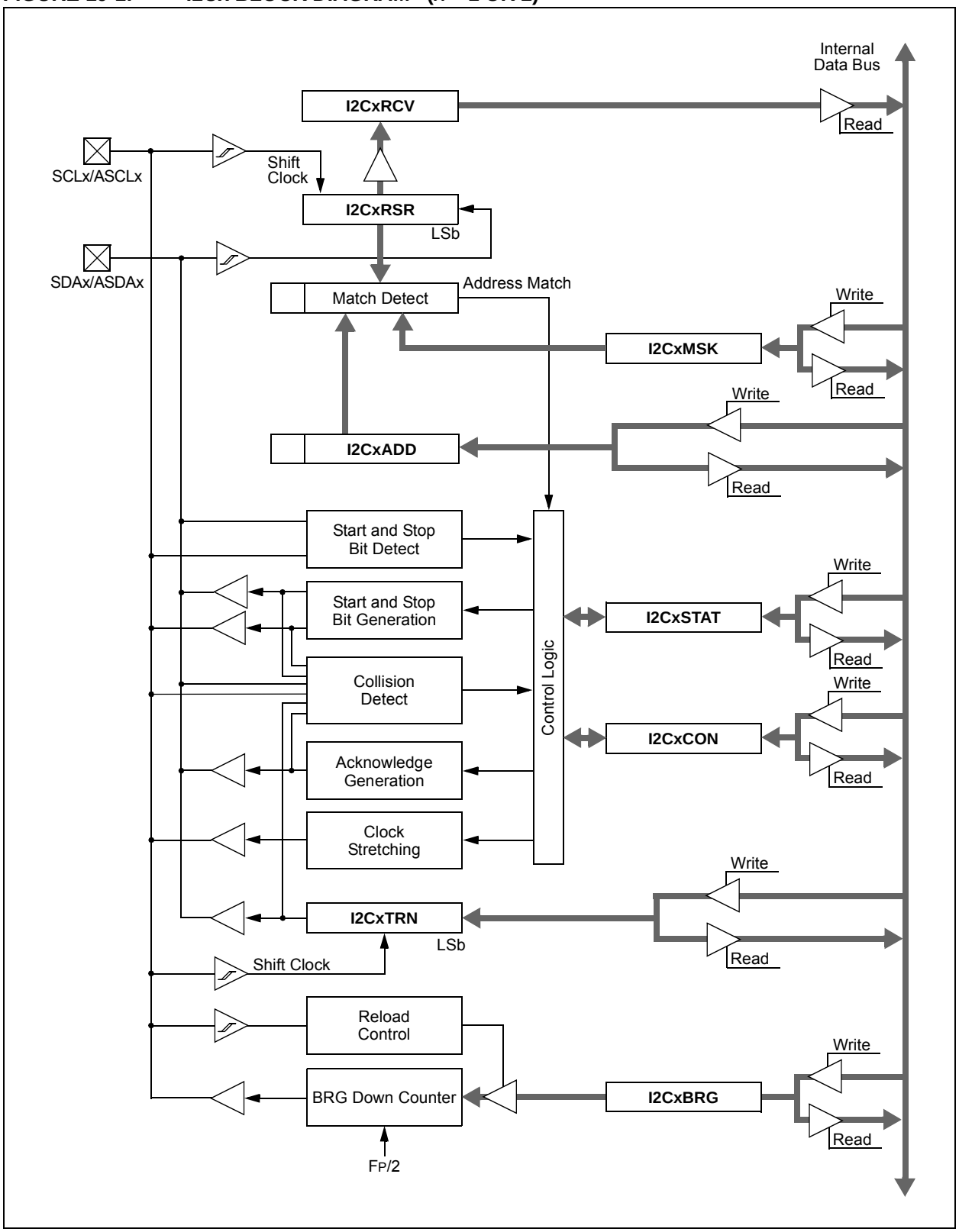
bit 2 **HOMIEN:** Home Input Event Interrupt Enable bit
1 = Interrupt is enabled
0 = Interrupt is disabled

bit 1 **IDXIRQ:** Status Flag for Index Event Status bit
1 = Index event has occurred
0 = No Index event has occurred

bit 0 **IDXIEN:** Index Input Event Interrupt Enable bit
1 = Interrupt is enabled
0 = Interrupt is disabled

Note 1: This status bit is only applicable to PIMOD<2:0> modes, '011' and '100'.

FIGURE 19-1: I2Cx BLOCK DIAGRAM (x = 1 OR 2)



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REGISTER 21-2: CxCTRL2: ECANx CONTROL REGISTER 2

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

U-0	U-0	U-0	R-0	R-0	R-0	R-0	R-0
—	—	—	DNCNT4	DNCNT3	DNCNT2	DNCNT1	DNCNT0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-5 **Unimplemented:** Read as ‘0’

bit 4-0 **DNCNT<4:0>:** DeviceNet™ Filter Bit Number bits

10010-11111 = Invalid selection
10001 = Compares up to Data Byte 3, bit 6 with EID<17>
•
•
•
00001 = Compares up to Data Byte 1, bit 7 with EID<0>
00000 = Does not compare data bytes

BUFFER 21-7: ECAN™ MESSAGE BUFFER WORD 6

R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
Byte 7							
bit 15							bit 8

R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
Byte 6							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-8 **Byte 7<15:8>:** ECAN Message Byte 7 bits

bit 7-0 **Byte 6<7:0>:** ECAN Message Byte 6 bits

BUFFER 21-8: ECAN™ MESSAGE BUFFER WORD 7

U-0	U-0	U-0	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
—	—	—	FILHIT4(1)	FILHIT3(1)	FILHIT2(1)	FILHIT1(1)	FILHIT0(1)
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-13 **Unimplemented:** Read as ‘0’

bit 12-8 **FILHIT<4:0>:** Filter Hit Code bits(1)

Encodes number of filter that resulted in writing this buffer.

bit 7-0 **Unimplemented:** Read as ‘0’

Note 1: Only written by module for receive buffers, unused for transmit buffers.

REGISTER 25-5: CMxMSKCON: COMPARATOR x MASK GATING CONTROL REGISTER

R/W-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
HLMS	—	OCEN	OCNEN	OBEN	OBNEN	OAEN	OANEN
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
NAGS	PAGS	ACEN	ACNEN	ABEN	ABNEN	AAEN	AANEN
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **HLMS:** High or Low-Level Masking Select bits
1 = The masking (blanking) function will prevent any asserted ('0') comparator signal from propagating
0 = The masking (blanking) function will prevent any asserted ('1') comparator signal from propagating

bit 14 **Unimplemented:** Read as '0'

bit 13 **OCEN:** OR Gate C Input Enable bit
1 = MCI is connected to OR gate
0 = MCI is not connected to OR gate

bit 12 **OCNEN:** OR Gate C Input Inverted Enable bit
1 = Inverted MCI is connected to OR gate
0 = Inverted MCI is not connected to OR gate

bit 11 **OBEN:** OR Gate B Input Enable bit
1 = MBI is connected to OR gate
0 = MBI is not connected to OR gate

bit 10 **OBNEN:** OR Gate B Input Inverted Enable bit
1 = Inverted MBI is connected to OR gate
0 = Inverted MBI is not connected to OR gate

bit 9 **OAEN:** OR Gate A Input Enable bit
1 = MAI is connected to OR gate
0 = MAI is not connected to OR gate

bit 8 **OANEN:** OR Gate A Input Inverted Enable bit
1 = Inverted MAI is connected to OR gate
0 = Inverted MAI is not connected to OR gate

bit 7 **NAGS:** AND Gate Output Inverted Enable bit
1 = Inverted ANDI is connected to OR gate
0 = Inverted ANDI is not connected to OR gate

bit 6 **PAGS:** AND Gate Output Enable bit
1 = ANDI is connected to OR gate
0 = ANDI is not connected to OR gate

bit 5 **ACEN:** AND Gate C Input Enable bit
1 = MCI is connected to AND gate
0 = MCI is not connected to AND gate

bit 4 **ACNEN:** AND Gate C Input Inverted Enable bit
1 = Inverted MCI is connected to AND gate
0 = Inverted MCI is not connected to AND gate

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TABLE 27-2: CONFIGURATION BITS DESCRIPTION (CONTINUED)

Bit Field	Description
WDTPRE	Watchdog Timer Prescaler bit 1 = 1:128 0 = 1:32
WDTPOST<3:0>	Watchdog Timer Postscaler bits 1111 = 1:32,768 1110 = 1:16,384 • • • 0001 = 1:2 0000 = 1:1
WDTWIN<1:0>	Watchdog Window Select bits 11 = WDT window is 25% of WDT period 10 = WDT window is 37.5% of WDT period 01 = WDT window is 50% of WDT period 00 = WDT window is 75% of WDT period
ALTI2C1	Alternate I2C1 pin 1 = I2C1 is mapped to the SDA1/SCL1 pins 0 = I2C1 is mapped to the ASDA1/ASCL1 pins
ALTI2C2	Alternate I2C2 pin 1 = I2C2 is mapped to the SDA2/SCL2 pins 0 = I2C2 is mapped to the ASDA2/ASCL2 pins
JTAGEN(2)	JTAG Enable bit 1 = JTAG is enabled 0 = JTAG is disabled
ICS<1:0>	ICD Communication Channel Select bits 11 = Communicate on PGEC1 and PGED1 10 = Communicate on PGEC2 and PGED2 01 = Communicate on PGEC3 and PGED3 00 = Reserved, do not use

Note 1: This bit is only available on dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X devices.

2: When JTAGEN = 1, an internal pull-up resistor is enabled on the TMS pin. Erased devices default to JTAGEN = 1. Applications requiring I/O pins in a high-impedance state (tri-state) in Reset should use pins other than TMS for this purpose.

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FIGURE 30-19: SPI2 SLAVE MODE (FULL-DUPLEX, CKE = 1, CKP = 1, SMP = 0) TIMING CHARACTERISTICS

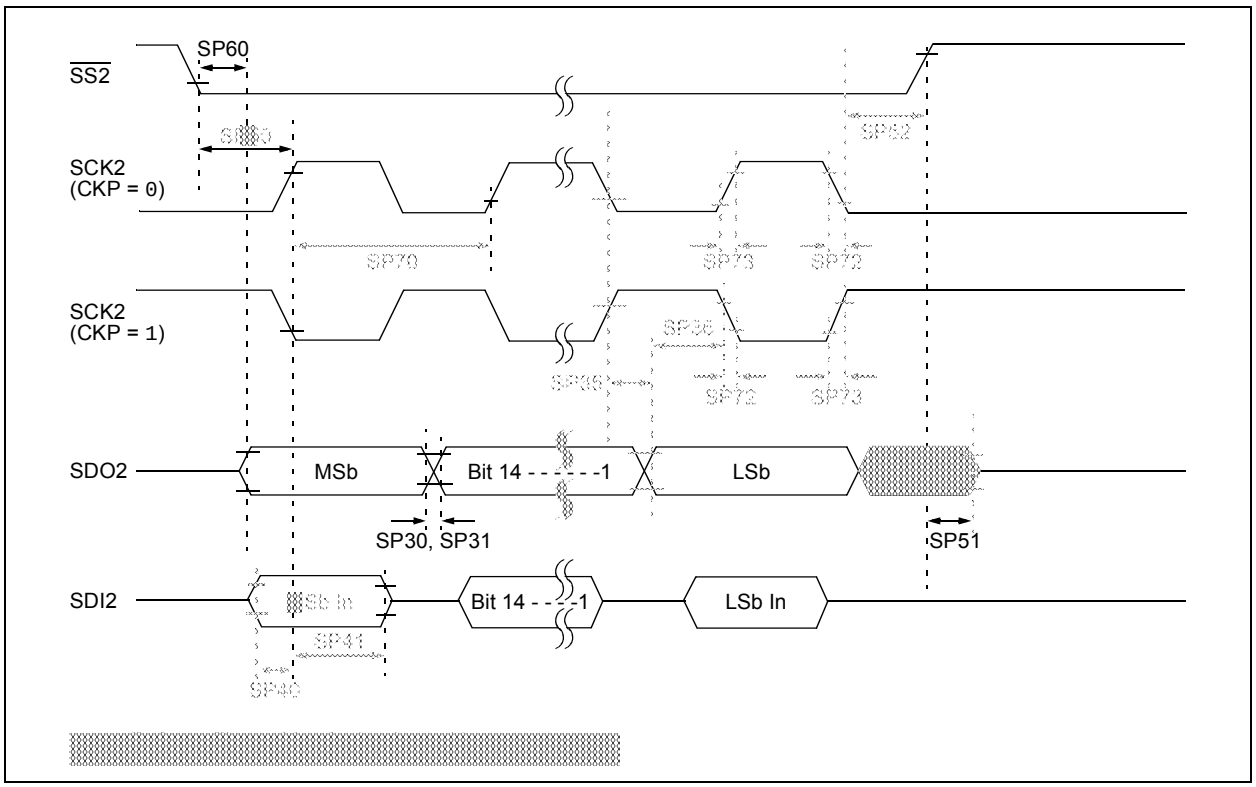

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TABLE 30-40: SPI2 SLAVE MODE (FULL-DUPLEX, CKE = 0, CKP = 0, SMP = 0) TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param.	**Symbol**	**Characteristic(1)**	**Min.**	**Typ.(2)**	**Max.**	**Units**	**Conditions**
SP70	FscP	Maximum SCK2 Input Frequency	—	—	11	MHz	**(Note 3)**
SP72	TscF	SCK2 Input Fall Time	—	—	—	ns	See Parameter DO32 **(Note 4)**
SP73	TscR	SCK2 Input Rise Time	—	—	—	ns	See Parameter DO31 **(Note 4)**
SP30	TdoF	SDO2 Data Output Fall Time	—	—	—	ns	See Parameter DO31 **(Note 4)**
SP31	TdoR	SDO2 Data Output Rise Time	—	—	—	ns	See Parameter DO31 **(Note 4)**
SP35	TscH2doV, TscL2doV	SDO2 Data Output Valid after SCK2 Edge	—	6	20	ns	
SP36	TdoV2scH, TdoV2scL	SDO2 Data Output Setup to First SCK2 Edge	30	—	—	ns	
SP40	TdiV2scH, TdiV2scL	Setup Time of SDI2 Data Input to SCK2 Edge	30	—	—	ns	
SP41	TscH2diL, TscL2diL	Hold Time of SDI2 Data Input to SCK2 Edge	30	—	—	ns	
SP50	TssL2scH, TssL2scL	$\overline{SS2}$ ↓ to SCK2 ↑ or SCK2 ↓ Input	120	—	—	ns	
SP51	TssH2doZ	$\overline{SS2}$ ↑ to SDO2 Output High-Impedance	10	—	50	ns	**(Note 4)**
SP52	TscH2ssH TscL2ssH	$\overline{SS2}$ ↑ after SCK2 Edge	1.5 TCY + 40	—	—	ns	**(Note 4)**

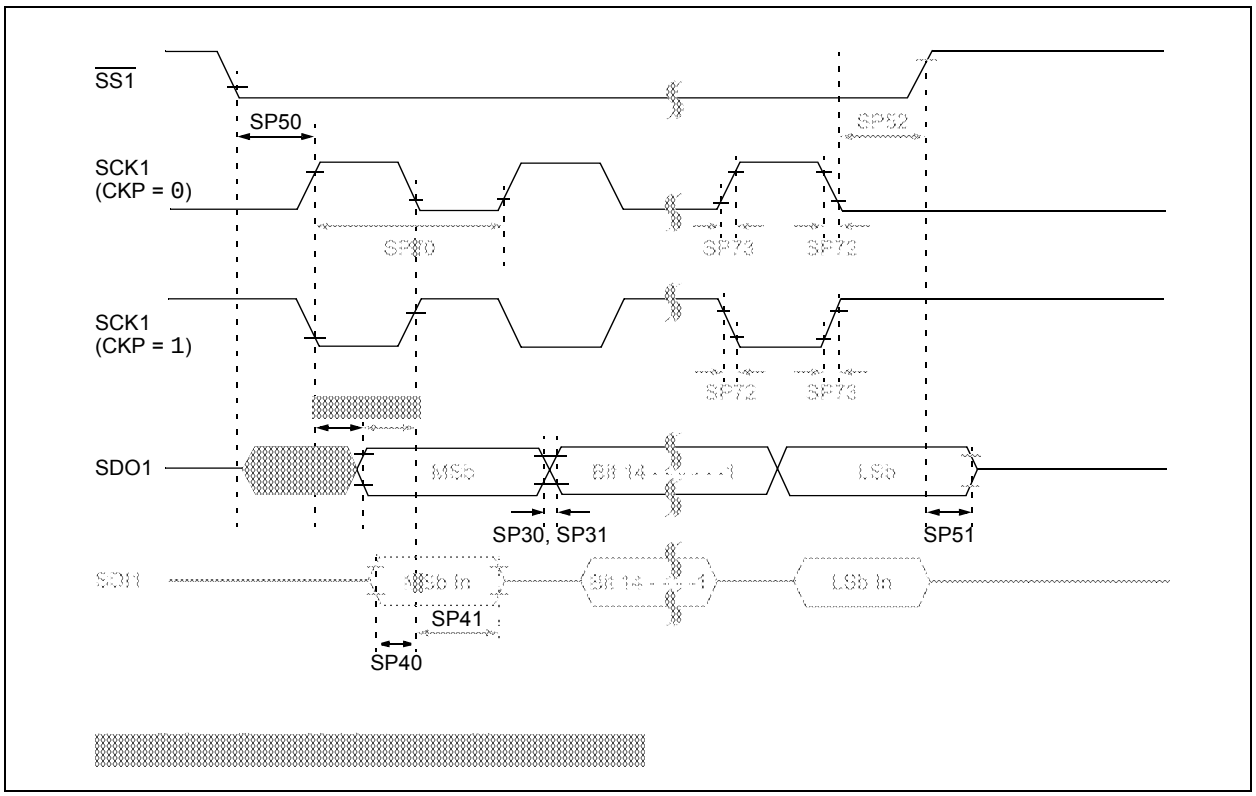
Note 1: These parameters are characterized, but are not tested in manufacturing.

2: Data in "Typical" column is at 3.3V, +25°C unless otherwise stated.

3: The minimum clock period for SCK2 is 91 ns. Therefore, the SCK2 clock generated by the master must not violate this specification.

4: Assumes 50 pF load on all SPI2 pins.

FIGURE 30-29: SPI1 SLAVE MODE (FULL-DUPLEX, CKE = 0, CKP = 0, SMP = 0) TIMING CHARACTERISTICS



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31.0 HIGH-TEMPERATURE ELECTRICAL CHARACTERISTICS

This section provides an overview of dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X electrical characteristics for devices operating in an ambient temperature range of -40°C to +150°C.

The specifications between -40°C to +150°C are identical to those shown in **Section 30.0 "Electrical Characteristics"** for operation between -40°C to +125°C, with the exception of the parameters listed in this section.

Parameters in this section begin with an H, which denotes High temperature. For example, Parameter DC10 in **Section 30.0 "Electrical Characteristics"** is the Industrial and Extended temperature equivalent of HDC10.

Absolute maximum ratings for the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X high-temperature devices are listed below. Exposure to these maximum rating conditions for extended periods can affect device reliability. Functional operation of the device at these or any other conditions above the parameters indicated in the operation listings of this specification is not implied.

Absolute Maximum Ratings(1)

Ambient temperature under bias(2) ..... -40°C to +150°C
Storage temperature ..... -65°C to +160°C
Voltage on V_{DD} with respect to V_{SS} ..... -0.3V to +4.0V
Voltage on any pin that is not 5V tolerant with respect to V_{SS}(3) ..... -0.3V to (V_{DD} + 0.3V)
Voltage on any 5V tolerant pin with respect to V_{SS} when V_{DD} < 3.0V(3) ..... -0.3V to 3.6V
Voltage on any 5V tolerant pin with respect to V_{SS} when $V_{DD} \geq 3.0V$(3) ..... -0.3V to 5.5V
Maximum current out of V_{SS} pin ..... 60 mA
Maximum current into V_{DD} pin(4) ..... 60 mA
Maximum junction temperature ..... +155°C
Maximum current sourced/sunk by any 4x I/O pin ..... 10 mA
Maximum current sourced/sunk by any 8x I/O pin ..... 15 mA
Maximum current sunk by all ports combined ..... 70 mA
Maximum current sourced by all ports combined(4) ..... 70 mA

Note 1: Stresses above those listed under "Absolute Maximum Ratings" can cause permanent damage to the device. This is a stress rating only, and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods can affect device reliability.

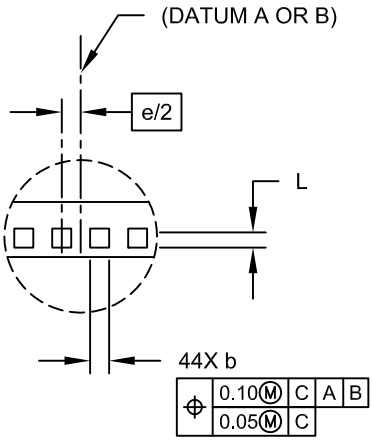
2: AEC-Q100 reliability testing for devices intended to operate at +150°C is 1,000 hours. Any design in which the total operating time from +125°C to +150°C will be greater than 1,000 hours is not warranted without prior written approval from Microchip Technology Inc.

3: Refer to the **"Pin Diagrams"** section for 5V tolerant pins.

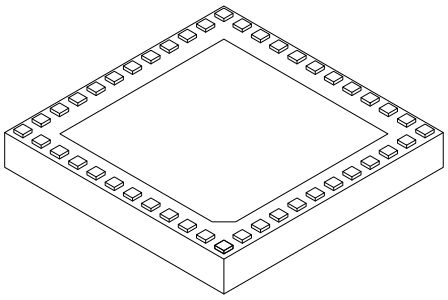
4: Maximum allowable current is a function of device maximum power dissipation (see Table 31-2).

44-Terminal Very Thin Leadless Array Package (TL) – 6x6x0.9 mm Body With Exposed Pad [VTLA]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



DETAIL A



Units		MILLIMETERS		
Dimension	Limits	MIN	NOM	MAX
Number of Pins	N		44	
Number of Pins per Side	ND		12	
Number of Pins per Side	NE		10	
Pitch	e		0.50 BSC	
Overall Height	A	0.80	0.90	1.00
Standoff	A1	0.025	-	0.075
Overall Width	E		6.00 BSC	
Exposed Pad Width	E2	4.40	4.55	4.70
Overall Length	D		6.00 BSC	
Exposed Pad Length	D2	4.40	4.55	4.70
Contact Width	b	0.20	0.25	0.30
Contact Length	L	0.20	0.25	0.30
Contact-to-Exposed Pad	K	0.20	-	-

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Package is saw singulated.
3. Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.
REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-157C Sheet 2 of 2

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